

PAGE 1 OF 1

**APPLICATION FOR UNITED STATES PATENT**  
**DECLARATION AND POWER OF ATTORNEY**

As a below named inventor, I declare that my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor if only one name is listed below, or an original, first and joint inventor if plural inventors are named below, of the subject matter which is claimed and for which a patent is sought on the invention entitled as set forth below, which is described in the attached specification; that I have reviewed and understand the contents of the specification, including the claims, as amended by any amendment specifically referred to in the oath or declaration; that no application for patent or inventor's certificate on this invention has been filed by me or my legal representatives or assigns in any country foreign to the United States of America; and that I acknowledge my duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, Section 1.56;

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

<b>TITLE OF INVENTION:</b> <p style="text-align: center; margin-top: 10px;"><b>Method and Apparatus for Flip Chip Device Assembly by Radiant Heating</b></p>		
<b>POWER OF ATTORNEY:</b> I HEREBY APPOINT PRACTITIONERS AT CUSTOMER NUMBER <b>23494</b> TO PROSECUTE THIS APPLICATION AND TRANSACT ALL BUSINESS IN THE PATENT AND TRADEMARK OFFICE CONNECTED THEREWITH		
<b>SEND CORRESPONDENCE TO:</b> Gary C. Honeycutt Texas Instruments Incorporated P.O. Box 655474, MS 3999 Dallas, TX 75265		<b>DIRECT TELEPHONE CALLS TO:</b> Gary C. Honeycutt (972) 238-7160
<b>NAME OF INVENTOR:</b> (1) Jimmy Liang	<b>NAME OF INVENTOR:</b> (2) Kevin Jin	<b>NAME OF INVENTOR:</b> (3) T.T. Chiu
<b>RESIDENCE &amp; POST OFFICE ADDRESS:</b> 2 <sup>nd</sup> Floor, #14-17, I-chen street, Nan-Kong area Taipei City, Taiwan	<b>RESIDENCE &amp; POST OFFICE ADDRESS:</b> 5F, 25, Chien-Hsing St. Hsin-Tien City, Taipei, Taiwan	<b>RESIDENCE &amp; POST OFFICE ADDRESS:</b> 4F, 16, Lane 7, Sec 2, Shiue Fu Rd. Tu Cheng City, Taipei, Taiwan
<b>COUNTRY OF CITIZENSHIP:</b> Taiwan, R.O.C.	<b>COUNTRY OF CITIZENSHIP:</b> Taiwan, R.O.C.	<b>COUNTRY OF CITIZENSHIP:</b> Taiwan, R.O.C.
<b>SIGNATURE OF INVENTOR:</b>	<b>SIGNATURE OF INVENTOR:</b>	<b>SIGNATURE OF INVENTOR:</b>
<b>DATE:</b>	<b>DATE:</b>	<b>DATE:</b>



<b>FORM PTO-1595</b> <b>TI-32508</b>		<b>RECORDATION FORM COVER SHEET</b> <b>PATENTS ONLY</b>		<b>U.S. Department of Commerce</b> <b>Patent and Trademark Office</b>					
To the Assistant Commissioner for Patents. Please record the attached original documents or copy thereof.									
<b>1. Name of conveying party(ies):</b>  Jimmy Liang      1/21/02 Kevin Jin        1/30/02 T.T. Chiu         1/30/02			<b>2. Name and Address of receiving party(ies):</b>  Name: TEXAS INSTRUMENTS INCORPORATED  Address: P.O. Box 655474, MS 3999  City: Dallas  State: TX      Zip: 75265  Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No						
<b>3. Nature of Conveyance:</b>  <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Other _____  Execution Date in order of listed parties: 1/21/02; 1/30/02; 1/30/02									
<b>4. Application number(s) or patent number(s).</b> This document is being filed together with a new application.  Execution date of the application in order of listed parties: 1/21/02; 1/30/02; 1/30/02 Title: Method and Apparatus for Flip Chip Device Assembly by Radian Heating Docket No: TI-32508  <table style="width: 100%;"> <tr> <td style="width: 50%;"> <b>A. Patent Application No.(s)</b>            S.N. 10/032,907         </td> <td style="width: 50%;"> <b>B. Patent No.(s)</b>            X,XXX,XXX         </td> </tr> <tr> <td style="text-align: right;">Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</td> <td style="text-align: right;">Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</td> </tr> </table>						<b>A. Patent Application No.(s)</b> S.N. 10/032,907	<b>B. Patent No.(s)</b> X,XXX,XXX	Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No
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<b>5. Name and address of party to whom correspondence concerning document should be mailed:</b>  Name: Gary C. Honeycutt Texas Instruments Incorporated  Address: P.O. Box 655474, MS 3999  City: Dallas  State: TX      Zip: 75265			<b>6. Number of applications and patents involved:</b> (1)						
			<b>7. Amount of fee enclosed or authorized to be charged:</b> \$40						
			<b>8. Deposit Account No:</b> 20-0668 (Attach duplicate copy if paying by deposit account)						
<b>DO NOT USE THIS SPACE</b>									
<b>9. Statement and signature.</b>  To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.  <div style="display: flex; justify-content: space-between;"> <div style="width: 40%;">           Date <u>3/8/02</u> </div> <div style="width: 50%; text-align: right;">             Gary C. Honeycutt, Reg. No. 20,250         </div> </div>									
Total Number of Pages including Cover Sheet, Attachments and Document: <u>2</u>									

ATTORNEY DOCKET NO.

TI-32539

## ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and



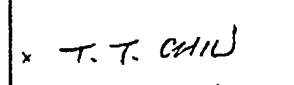
WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 7839 Churchill Way, MS 3999, Dallas, Texas 75251, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE OF INVENTION	Method and Apparatus for Flip Chip Device Assembly by Radiant Heating		
SIGNATURE OF INVENTOR AND NAME	x  Jimmy Liang	x  Kevin Jin	x  T.T. Chiu
DATE OF SIGNATURE	x Jan. 21, 2002	x Jan. 30, 2002	x Jan. 30, 2002
RESIDENCE (City, State)	Taipei, Taiwan	Taipei, Taiwan	Taipei, Taiwan
DATE APPLICATION EXECUTED			

After recording Assignment, please return to:

Gary C. Honeycutt  
Texas Instruments Incorporated  
P.O. Box 655474, MS 3999  
Dallas, TX 75265



COPY OF PAPERS  
ORIGINALLY FILED


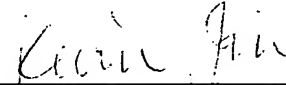
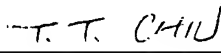
ATTORNEY'S DOCKET NO.

TI-32508

**APPLICATION FOR UNITED STATES PATENT  
DECLARATION AND POWER OF ATTORNEY**

As a below named inventor, I declare that my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor if only one name is listed below, or an original, first and joint inventor if plural inventors are named below, of the subject matter which is claimed and for which a patent is sought on the invention entitled as set forth below, which is described in the attached specification of Application Serial No. 10/032,907, filed 12/28/01; that I have reviewed and understand the contents of the specification, including the claims, as amended by any amendment specifically referred to in the oath or declaration; that no application for patent or inventor's certificate on this invention has been filed by me or my legal representatives or assigns in any country foreign to the United States of America; and that I acknowledge my duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, Section 1.56;

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COUNTRY OF CITIZENSHIP:  Taiwan, R.O.C.	COUNTRY OF CITIZENSHIP:  Taiwan, R.O.C.	COUNTRY OF CITIZENSHIP:  Taiwan, R.O.C.
SIGNATURE OF INVENTOR:  * 	SIGNATURE OF INVENTOR:  * 	SIGNATURE OF INVENTOR:  * 
DATE:  * Jan. 21, 2002	DATE:  * Jan. 30, 2002	DATE:  * Jan. 30, 2002